

Title (en)
SEMIFINISHED PRODUCT FOR ELECTRICAL CONTACTS, MADE OF A COMPOSITE MATERIAL BASED ON SILVER AND TIN OXIDE, AND POWDER METALLURGICAL PROCESS FOR PRODUCING IT

Title (de)
HALBZEUG FÜR ELEKTRISCHE KONTAKTE AUS EINEM VERBUNDWERKSTOFF AUF SILBER-ZINNOXID-BASIS UND PULVERMETALLURGISCHES VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)
PRODUIT SEMI-FINI POUR CONTACTS ELECTRIQUES, CONSTITUE D'UN MATERIAU COMPOSITE A BASE D'ARGENT ET D'OXYDE D'ETAIN, ET PROCEDE DE METALLURGIE DES POUDRES POUR SA FABRICATION

Publication
EP 0440620 B2 19980603 (DE)

Application
EP 89903734 A 19890322

Priority
• DE 3810311 A 19880326
• EP 8900316 W 19890322

Abstract (en)
[origin: WO8909478A1] A semifinished product for electrical contacts, made of a composite material based on silver and tin oxide, has a microstructure in which regions containing little or no metallic oxide alternate with regions in which all or most of the metallic oxide component is finely distributed. Also described is a powder metallurgical process for producing the product.

IPC 1-7
H01H 1/02; H01H 11/04

IPC 8 full level
B22F 9/24 (2006.01); **B22F 1/12** (2022.01); **C22C 1/05** (2006.01); **C22C 5/06** (2006.01); **C22C 32/00** (2006.01); **H01H 1/02** (2006.01); **H01H 1/023** (2006.01); **H01H 1/0237** (2006.01); **H01H 11/04** (2006.01)

CPC (source: EP US)
B22F 1/12 (2022.01 - EP US); **C22C 32/0021** (2013.01 - EP US); **H01H 1/02376** (2013.01 - EP US); **H01H 11/048** (2013.01 - EP US); **B22F 2998/10** (2013.01 - EP US); **Y10T 428/12014** (2015.01 - EP US); **Y10T 428/12021** (2015.01 - EP US); **Y10T 428/12028** (2015.01 - EP US); **Y10T 428/1216** (2015.01 - EP US); **Y10T 428/12167** (2015.01 - EP US)

C-Set (source: EP US)
B22F 2998/10 + B22F 1/12 + B22F 9/026 + B22F 9/30

Designated contracting state (EPC)
AT BE CH DE FR GB IT LI LU NL SE

DOCDB simple family (publication)
WO 8909478 A1 19891005; CA 1339713 C 19980317; CN 1022934 C 19931201; CN 1036991 A 19891108; DD 283571 A5 19901017; DE 3909384 A1 19891019; DE 58907140 D1 19940407; EP 0440620 A1 19910814; EP 0440620 B1 19940302; EP 0440620 B2 19980603; ES 2012293 A6 19900301; JP H03504615 A 19911009; US 5360673 A 19941101

DOCDB simple family (application)
EP 8900316 W 19890322; CA 594639 A 19890323; CN 89101699 A 19890327; DD 32685689 A 19890323; DE 3909384 A 19890322; DE 58907140 T 19890322; EP 89903734 A 19890322; ES 8901059 A 19890322; JP 50343289 A 19890322; US 54901590 A 19900917